



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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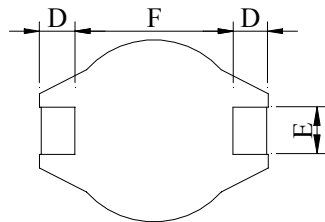
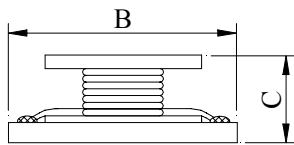
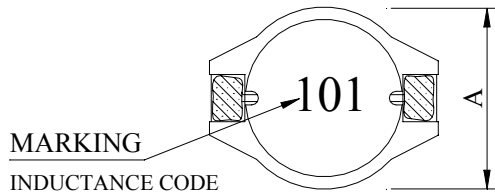
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



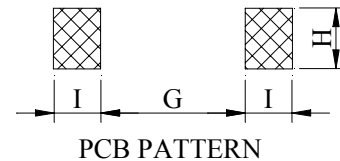
# PRODUCT SPECIFICATION

Product Name	3316 SMD POWER INDUCTORS - OPEN TYPE	Page	1
TAMURA Part No.	TO3316-XXX□	Rev. No.	0

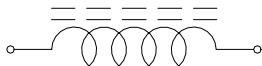
## 1. CONFIGURATION & DIMENSIONS :



A	: 10.0±0.2	m/m
B	: 12.7±0.2	m/m
C	: 5.0±0.3	m/m
D	: 2.4±0.2	m/m
E	: 2.2±0.2	m/m
F	: 7.6±0.3	m/m
G	: 7.3 REF.	m/m
H	: 2.8 REF.	m/m
I	: 3.0 REF.	m/m



## 2. SCHEMATIC DIAGRAM :



## 3. GENERAL SPECIFICATION :

- a) TEMP. RISE : 40°C TYP.
- b) RATED CURRENT : BASE ON TEMP. RISE &  $\Delta$  LOA=10% TYP.
- c) STORAGE TEMP. : -40°C ~ +125°C
- d) OPERATING TEMP. : -25°C ~ +105°C
- e) RESISTANCE TO SOLDER HEAT : 260°C FOR 10 SECS.

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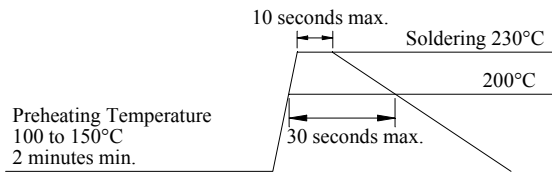
## 4. ELECTRICAL CHARACTERISTICS :

TAMURA Part No.	INDUCTANCE ( $\mu$ H)	Q REF.	TEST FREQ. (HZ)		SRF (MHZ) TYP.	RDC (mOhm) MAX	IDC (A)
			L	Q			
TO3316-1R0M	1.0 $\pm$ 20%	50	100K		150.0	9	6.8
TO3316-1R5M	1.5 $\pm$ 20%	50	100K		100.0	10	6.4
TO3316-2R2M	2.2 $\pm$ 20%	45	100K		85.0	12	6.1
TO3316-3R3M	3.3 $\pm$ 20%	35	100K		60.0	15	5.4
TO3316-4R7M	4.7 $\pm$ 20%	35	100K		45.0	18	4.8
TO3316-6R8M	6.8 $\pm$ 20%	35	100K		35.0	27	4.4
TO3316-100M	10.0 $\pm$ 20%	30	100K		25.0	38	3.9
TO3316-150M	15.0 $\pm$ 20%	30	100K		20.0	46	3.1
TO3316-220M	22.0 $\pm$ 20%	25	100K		18.0	85	2.7
TO3316-330M	33.0 $\pm$ 20%	30	100K		14.0	100	2.1
TO3316-470M	47.0 $\pm$ 20%	20	100K		11.0	140	1.8
TO3316-680M	68.0 $\pm$ 20%	35	100K		10.0	200	1.5
TO3316-101M	100.0 $\pm$ 20%	40	100K		7.0	280	1.3
TO3316-151M	150.0 $\pm$ 20%	40	100K		6.5	400	1.0
TO3316-221M	220.0 $\pm$ 20%	40	100K		5.0	610	0.8
TO3316-331M	330.0 $\pm$ 20%	60	100K		4.0	1020	0.6
TO3316-471M	470.0 $\pm$ 20%	50	100K		3.0	1270	0.5
TO3316-681M	680.0 $\pm$ 20%	65	100K		2.5	2020	0.4
TO3316-102M	1000.0 $\pm$ 20%	60	100K		2.0	3000	0.3

# PRODUCT SPECIFICATION

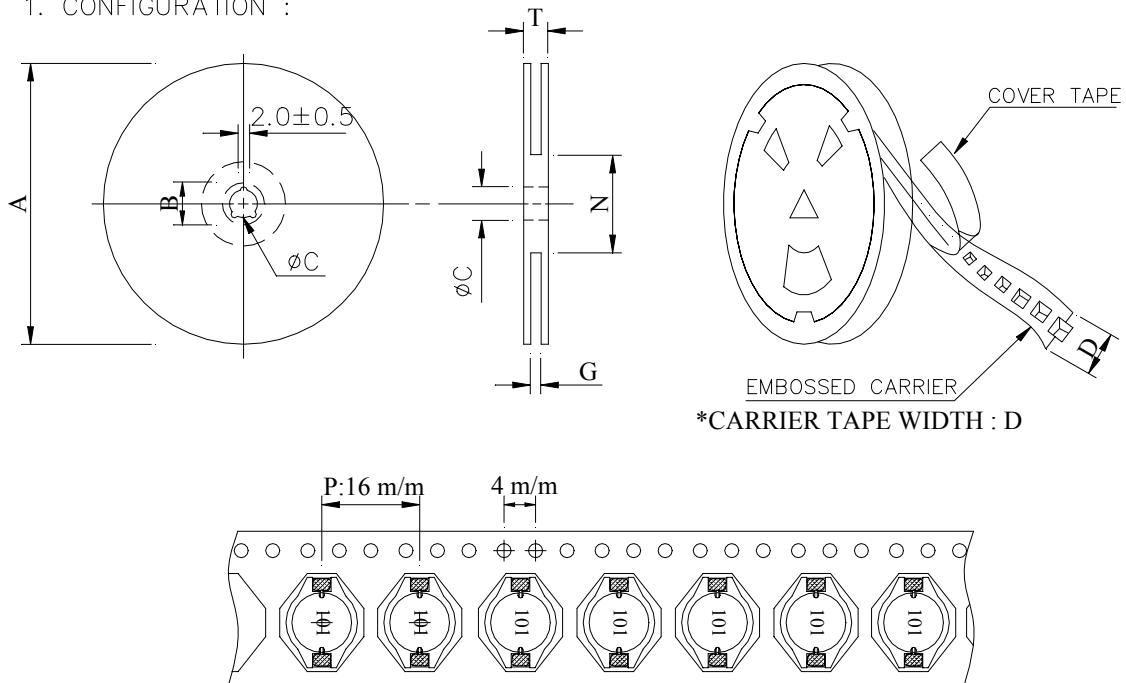
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MURA Part No.	TO3316-XXX□	Rev. No.	0

### RECOMMENDED SOLDERING CONDITIONS REFLOW SOLDERINGS



## PACKAGING INFORMATION :

### 1. CONFIGURATION :



### 2. DIMENSIONS : (m/m)

STYLE	A	B	C	D	G	N	T
13 - 24	330	21±0.8	13±0.5	24	26 MAX	50 MIN	30.4

### 3. Q'TY & G.W. PER PACKAGE :

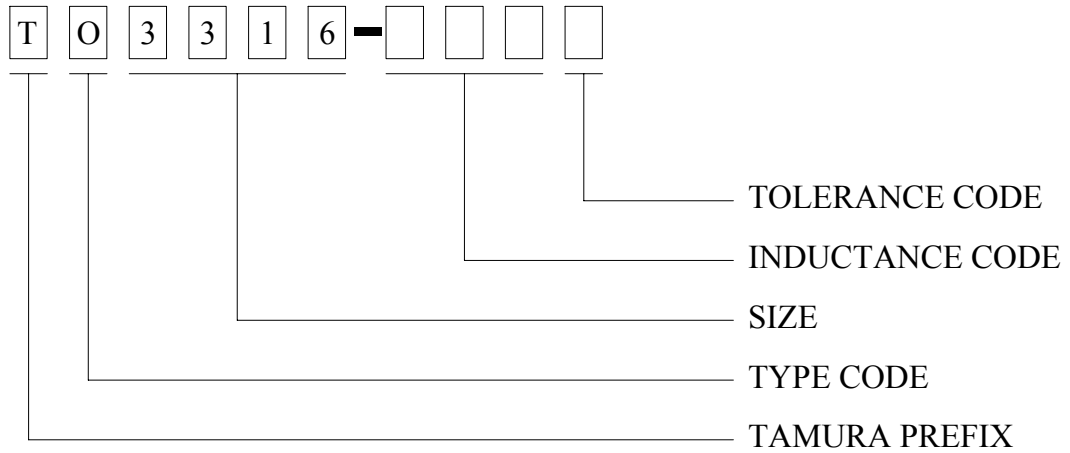
SERIES	INNER : REEL			OUTER : CARTON		
	Q'TY (PCS)	G.W. (gw)	STYLE	Q'TY (PCS)	G.W. (kg)	SIZE (cm)
T03316	500	1000	13 - 24	2000	5.5	40 x 40 x 24



# PRODUCT SPECIFICATION

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## 6. Part No. FORMAT :



# PRODUCT SPECIFICATION

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## 7. RELIABILITY TEST :

TEST ITEM	SPECIFICATION	TEST CONDITION										
SOLDERABILITY	MORE THAN 90% OF THE TERMINAL ELECTRODE SHALL BE COVERED WITH FRESH SOLDER.	PREHEAT : 125±25°C FOR 60 SECONDS SOLDER : H63A ( EUTECTIC SOLDER ) SOLDER TEMP. : 230±5°C FLUX : ROSIN DIP TIME : 4±1 SECONDS										
THERMAL SHOCK TEST  ( TEMP. CYCLE )	INDUCTANCE SHALL NOT CHANGE MORE THAN ±20%	<table style="width: 100%; border: none;"> <tr> <td style="width: 60%;">ROOM TEMP. —————→</td> <td style="width: 40%; text-align: center;">-25±2°C</td> </tr> <tr> <td>15 MINUTES</td> <td style="text-align: center;">30 MINUTES</td> </tr> <tr> <td colspan="2"> </td> </tr> <tr> <td>ROOM TEMP. —————→</td> <td style="text-align: center;">85±2°C</td> </tr> <tr> <td>15 MINUTES</td> <td style="text-align: center;">30 MINUTES</td> </tr> </table> TOTAL : 50 CYCLES	ROOM TEMP. —————→	-25±2°C	15 MINUTES	30 MINUTES			ROOM TEMP. —————→	85±2°C	15 MINUTES	30 MINUTES
ROOM TEMP. —————→	-25±2°C											
15 MINUTES	30 MINUTES											
ROOM TEMP. —————→	85±2°C											
15 MINUTES	30 MINUTES											
HUMIDITY RESISTANCE TEST		TEMPERATURE : 40±2°C HUMIDITY : 90 ~ 95% APPLIED CURRENT : PER SPEC. TIME : 500 HOURS										
HIGH TEMP. RESISTANCE TEST		TEMPERATURE : 85±2°C APPLIED CURRENT : PER SPEC. TIME : 500 HOURS										